



PCN# : P466AA
Issue Date : Sep. 29, 2014

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : Dec. 28, 2014

Expected First Date Code of Changed Product :1452

Description of Change (From) :

5-inch wafer fabrication line at Fairchild Semiconductor Bucheon, Korea

Description of Change (To) :

6-inch wafer fabrication line at Fairchild Semiconductor Bucheon Korea

Reason for Change:

Fairchild Semiconductor is increasing wafer fabrication capacity by qualifying an 6-in wafer fabrication line at Fairchild Semiconductor Bucheon Korea. Quality and reliability remain at the highest standards already demonstrated within Fairchild's existing products.

The reliability qualification results used to qualify the 6-in wafer fabrication line are summarized below. Design, die size and layout of the affected products will remain unchanged. There are no changes in the datasheet or electrical performance.

Affected Product(s): Please refer to the list of affected products in the addendum attached in the PCN email you received. This list is based on an analysis of your company's procurement history.

Qualification Plan	Device	Package	Process	No. of Lots
Q20140051	RURG8060_F085	TO247	Ultrafast	3

Test Description:	Condition:	Standard :	Duration:	Results:
High Temperature Reverse Bias	480V,175C	JESD22-A108	1000hrs	0/231
High Humidity High Temp. Reverse Bias(H3TRB)	85%RH, 85C,100V	JESD22-A101B	1000hrs	0/231
Autoclave	100%RH, 121C	JESD22-A102	96hrs	0/231
Temperature Cycle	-55C,150C	JESD22-A104	1000cycles	0/231
Power Cycle	, On/Off=2.0min, Delta Tj=100C	MIL-STD-750 M1037	6000cycles	0/77
High Temperature Storage Life	175C	JESD22-A103	1000hrs	0/231
Early Life Failure Rate with HTRB	600V, 175C	JESD22-A108	48hrs	0/1000
Charged Device Model ESD	Per AEC-Q101-005		N/A	0/10
Human Body Model ESD	Per AEC-Q101-001		N/A	0/10
Destructive Physical Analysis	Per AEC-Q101-004		N/A	0/21